ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention

METHOD FOR REACTIVE ION ETCH PROCESSING OF A DUAL DAMASCENE STRUCTURE

Application Number :

10/709,630

Confirmation Number:

First Named Applicant:

William America

Attorney Docket Number:

FIS920040053US1

Art Unit:

2825

Examiner:

B. KESHAVAN

Search string:

(6479391 or 6514852 or 6573176 or 6576482).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
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13K	3	6573176	2003-06-03	Hong	-	_	,
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11/22/2004				
Date				
11/22/2004				

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